

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) SOLDER BALL ALLOY:
 STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
 SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
 4) NON-SOLDER MASK DEFINED PAD.
 5) PAD Cu DIAMETER: 0.20mm.
 6) SUBSTRATE MATERIAL: Si (SILICON).
 7) DAISY CHAIN PATTERN (SEE PAGE 2).

SECTION A-A

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP264T.3C-DC173D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP264T.3C1-DC173D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.3	DRAWN J. Hines	1/16/11
X.XX	+/- 0.03		
X.XXX	+/- 0.003		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
□ INCHES □ MILLIMETERS		QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

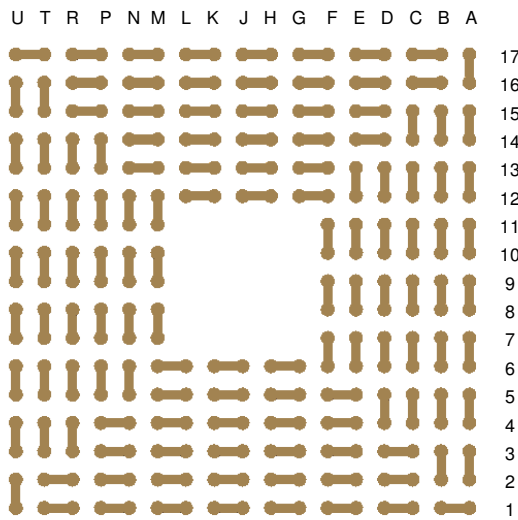
TopLine®

TITLE WLP264T.3C-DC173D
 264-BALL P=0.3mm (WLP264-5.96)

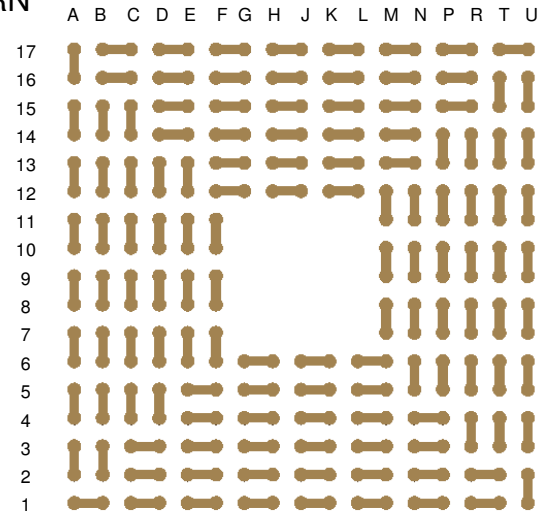
SCALE	SIZE	DRAWING NO.	REV
16.75:1	A	531732	A

DO NOT SCALE DRAWING SHEET 1 OF 2

BALL VIEW



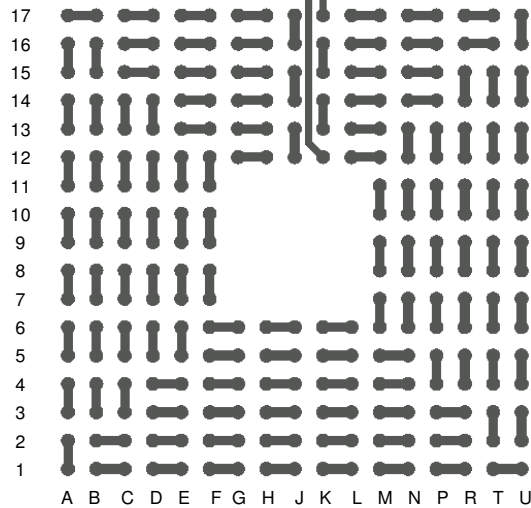
DAISY CHAIN PATTERN



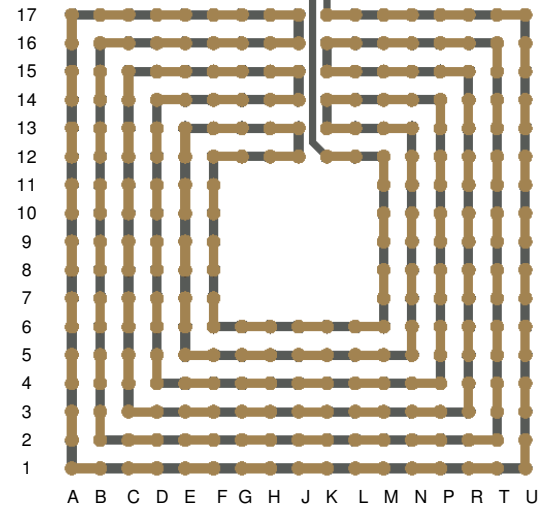
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

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TITLE			
WLP264T.3C-DC173D			
264-BALL P=0.3mm (WLP264-5.96)			
SCALE	SIZE	DRAWING NO.	REV
12.5:1	A	531732	A
DO NOT SCALE DRAWING			SHEET 2 OF 2